

# TriMet Hop<sup>®</sup> Extended Use (EU) Contactless Media

January 2024



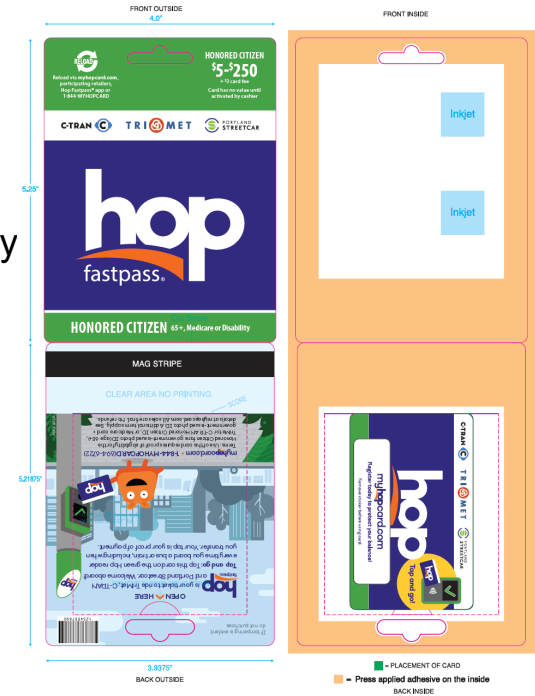
# Hop Cards Overview

## Current Contract:

- Expires May 2024
- Utilizes the MIFARE® DESFire® EV1 chip for Hop card manufacturing. Received notice in 2021 of the pending discontinuation of this technology
- 18 Variations of Fare Media + Packaging and special card runs

## Distribution channels:

- Non-Personalized Hop cards sold at ~360 retailers throughout region
- Personalized Cards distributed via CSC for fare programs
- Cards for special events/programs distributed thru partnerships



# Project Goals

- Continuation of Operations – seamless transition for Riders. All existing Hop cards will continue to be accepted.
- Upgrade chip technology - EV3 chips brings increased security for riders, higher level of support for authentication and data protection
- Stock Hop cards in Ticket Vending Machines (TVMs) for future rollout
- Position contractual terms to mitigate future chip shortages (keep a minimum of 400,000 chips / 52 weeks in inventory for TriMet utilization).
- Improve options for cards with unique graphics



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# Vendor Comparison

Differences	<u>ABC</u> Corp	Paragon ID
Price per Full Fare Card	\$1.66	\$1.43
Exceptions to RFP Requirements	<u>None</u>	Nine Exceptions
Price Increases over Course of Contract	Accepted benchmarked index for permissible annual price increases	Requested an exception to end contract if parties couldn't agree on annual price increase
Manufacturing Turnaround Time	Able to meet eight week requirement	Requested an exception of 10-12 weeks
Quality Control Expectations	Able to meet 0.1% allowable defect rate	Requested an exception of 2% defect rate
Supply Chain	Proven capacity to successfully navigate supply chain interruptions	Unknown
EV3 tech understanding	Reference Customer: has provided over 1M EV3 chip cards to ORCA	Did not provide an EV3 chip customer reference
Simplified onboarding process and timeline	As incumbent vendor, all processes and cards are set up with the exception of the new chip	Risk to timeline for onboarding a new manufacturer